

Part Number: **BZX84Cxx-p-F (Date Code 0833+)**
Weight (mg): 8.487

p = package designator
See Data Sheet

XX= 10, 11, 12, 13, 15, 16, 18, 20, 22, 24, 27, 2V4,
2V7, 30, 33, 36, 39, 3V0, 3V3, 3V6, 3V9, 4V3,
4V7, 5V1, 5V6, 6V2, 6V8, 7V5, 8V2, 9V1

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Material(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Doped Silicon*	7440-21-3	100.00%	0.76%	0.0647	1000000	7623
Leadframe	Alloy 42	Fe	7439-89-6	57.65%	28.79%	2.4432	576500	165952
		Ni	7440-02-0	41.00%			410000	118023
		Mn	7439-96-5	0.60%			6000	1727
		Cr(not Cr 6+)	7440-47-3	0.10%			1000	288
		Co	7440-48-4	0.50%			5000	1439
		Si	7440-21-3	0.15%			1500	432
Leadframe Plating	Silver	Silver	7440-22-4	100.00%	1.22%	0.1034	1000000	12183
Bond Wire	Gold Wire	Gold	7440-57-5	100.00%	0.10%	0.0082	1000000	966
Encapsulation	KTMC-1050G	SiO2	60676-86-0	69.00%	66.13%	5.6124	690000	456271
		Epoxy Resin	29690-82-2	14.00%			140000	92577
		Phenol Resin	9003-35-4	7.00%			70000	46288
		Mg(OH)2	1309-42-8	8.00%			80000	52901
		C	1333-86-4	0.20%			2000	1323
		others	----	1.80%			18000	11903
		Tin	7440-31-5	100.00%			3.01%	0.2555
Lead Plating Finish	Matte Tin	Tin	7440-31-5	100.00%	3.01%	0.2555	1000000	30103
				Total	100.00	8.4874		1000000

Tolerance ±10%

This data is based on information provided by our suppliers. We believe it to be correct but do not routinely validate it by measurement. It is for guidance only and Diodes Inc. does not guarantee its absolute accuracy or completeness

* The Silicon Chip is doped at atomic levels with trace amounts of elements that may include Phosphorus, Boron, Arsenic, and other elements. Metalization may include Titanium, Nickel, Aluminum, Silver or Gold. These substances are not reported where their concentration is less than the minimum reportable level per the guidelines specified in the Tables of EIA JIG-101, [Material Composition Declaration for Electronic Products](#).

This product or product family does not contain any of the following substances except as **CURRENTLY** exempted by ELV II and RoHS and reported above:

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|--|---|
| Asbestos | Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.) |
| Azo compounds | Ozone Depleting Substances - Class II (HCFCs) |
| Cadmium and cadmium compounds | Perfluorooctane Sulphonate (PFOS) or related compounds |
| Certain Shortchain Chlorinated Paraffins | Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including DecaBDE |
| Chlorinated organic compounds | Polychlorinated Biphenyls (PCBs) |
| Hexavalent chromium compounds | Polychlorinated Naphthalenes (> 3 chlorine atoms) |
| Lead and lead compounds | Radioactive Substances |
| Mercury and mercury compounds | Tributyl Tin (TBT) and Triphenyl Tin (TPT) |
| Organic tin compounds | Tributyl Tin Oxide (TBTO) |